



DOCKET: FIS920030315US1

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

INVENTOR: Edmund D. Blackshear)
SERIAL NO.: 10/719,334)
FILING DATE: November 21, 2003) DATE: May 11, 2006
FOR: OVERLAP STACKING OF CENTER BUS BONDED MEMORY CHIPS FOR
DOUBLE DENSITY AND METHOD OF MANUFACTURING THE SAME

CHANGE OF CORRESPONDENCE ADDRESS FOR ALL PURPOSES


Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Pursuant to 37 CFR §1.33, please change the correspondence address, (Customer No. 32074), for all purposes for the above identified patent application and resulting patent to:

**INTERNATIONAL BUSINESS MACHINES CORPORATION
Intellectual Property Law/Zip 482
2070 Route 52
Hopewell Junction, New York 12533-6531**

Respectfully submitted,


Robert Curcio
Reg. No. 44,638